

## **WG 4 RF Power Couplers – Eiji Kako and Wolf-Dietrich Moeller, co-conveners**

The conveners seek short (3~5 slides), specific contributions under the following four topics regarding RF power couplers for SRF. Relevant poster contributions recycled from other venues are encouraged, as well as new recent results. We seek to stimulate active, informed discussion. Please contact Eiji Kako (eiji.kako-at-kek.jp) and/or Wolf-Dietrich Moeller (wolf-dietrich.moeller@desy.de) for contribution coordination.

**Tue., March 25th, 4 hours, 8:30 – 12:30**

1. Copper plating:
  - a. Copper plating specifications for projects
  - b. Copper plating methods; electrolytic, sputtering
  - c. Thermal simulations on TTF3 couplers; pulsed vs. CW
  - d. Investigation methods; destructive vs. non-destructive
  - e. Copper plating defects; classification
  - f. QC during mass production
2. Power coupler preparation before RF conditioning, and RF conditioning:
  - a. IFMIF
  - b. SPIRAL2
  - c. XFEL
  - d. KEK-STF, cERL
  - e. TTF3 –SLAC
  - f. ....
3. Power coupler design:
  - a. TTF3 CW development for LCLS-II
  - b. ANL coupler for FRIB
  - c. Coupler designed with HE 11 mode, SLAC
  - d. CW coupler for BERLinPro
  - e. CW coupler at TRIUMF
  - f. CW coupler at Cornell-ERL
  - g. ESS coupler design
  - h. ....